

# Mads Brincker

## List of Publications by Year in descending order

Source: <https://exaly.com/author-pdf/4480018/publications.pdf>

Version: 2024-02-01

9  
papers

69  
citations

1684188

5  
h-index

1588992

8  
g-index

9  
all docs

9  
docs citations

9  
times ranked

73  
citing authors

#	ARTICLE	IF	CITATIONS
1	Thermo-mechanically induced texture evolution and micro-structural change of aluminum metallization. Journal of Materials Science: Materials in Electronics, 2018, 29, 3898-3904.	2.2	6
2	Comparative Study of Al Metallization Degradation in Power Diodes Under Passive and Active Thermal Cycling. IEEE Transactions on Components, Packaging and Manufacturing Technology, 2018, 8, 2073-2080.	2.5	7
3	Low temperature transient liquid phase bonded Cu-Sn-Mo and Cu-Sn-Ag-Mo interconnects – A novel approach for hybrid metal baseplates. Microelectronics Reliability, 2018, 88-90, 774-778.	1.7	5
4	Strength and reliability of low temperature transient liquid phase bonded Cu Sn Cu interconnects. Microelectronics Reliability, 2017, 76-77, 378-382.	1.7	23
5	Theoretical analysis of microstructured gradient-index lens for THz photonics using Greens function integral equation methods. , 2016, , .		0
6	Microstructured gradient-index lenses for THz photoconductive antennas. AIP Advances, 2016, 6, .	1.3	9
7	Mechanisms of metallization degradation in high power diodes. Microelectronics Reliability, 2016, 64, 489-493.	1.7	5
8	Tunable local excitation of surface plasmon polaritons by sum-frequency generation in ZnO nanowires. Optics Communications, 2015, 356, 109-112.	2.1	1
9	Effects of thermal cycling on aluminum metallization of power diodes. Microelectronics Reliability, 2015, 55, 1988-1991.	1.7	13